CALL FOR PAPERS – MOBISLICE II – Mobility Support in Slice-based network control for heterogeneous environments

**Description**

Network slicing has been one of the key enabling technologies for the upcoming 5th Generation of Telecommunications. Alongside other important technologies, such as NFV, SDN and MEC, its contributions to isolated network provisioning in a more dynamic and flexible way are being pursued in different industry and academia arenas throughout the world. Nonetheless, considering the wide range of foreseen enhanced use cases (not only in scope of 5G but also Beyond-5G), slicing aspects have been mostly targeting either enhancements at the radio level, or the integration of cloud resourcing capabilities for supporting network operation at the core and/or the edge. As such, there is a wide gap related with the impact that such slicing-based procedures will exert over mobility management processes for seamless mobility support while the devices, network or services move both physically (i.e., change their network point of attachment) as well as virtually (i.e., between slices). It is evident that a vast majority of access to on-line services is done while on the move, and considers not only human-to-machine communications (such as ultra-HD video conferencing and other services) but also machine-to-machine communications (such as vehicles and drones/UAV’s for Internet of Things scenarios). The objective of the MOBISLICE II workshop is to foster the ideas of slice-based designs and technologies in mobile scenarios and assess their impact, proposing solutions and enhancements to their efficient, dynamic and elastic support.

**Topics**

- The MOBISLICE II workshop focuses, but is not limited to, the following topics targeting slicing:
  - Vertical use cases and architectures for MOBISLICE (IoT, Edge, etc.)
  - Automotive service and ITS scenarios
  - Teleco Operator and enterprise-based environments
  - Smart-X slice mobility
  - Management and orchestration for MOBISLICE
    - Common operations and API
    - Inter- and intra-slice mobility
    - Lifecycle management
    - Heterogeneous access convergence
    - High availability and reliability techniques
  - Standardization trends and activities for MOBISLICE
    - Status and progresses in 3GPP/ETSI/IEEE/5GAA and other SDOs
    - Proposals and standardization direction for advanced slicing
    - SDN/NFV initiatives
    - Slice-enhanced Networking and telecommunication protocols
  - Beyond-5G slicing
    - Disruptive architectures
    - Zero-touch slice performance

**Technical Program Committee**

- Alex Galis, UCL
- Antonio de la Oliva, UC3M
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- Yong-Hyuck Evan Kim, Qualcomm
- Younghan Kim, Soongsil Univ
- Pankaj Thorat, Samsung

**Submissions**

MOBISLICE II will accept papers formatted as the standard IEEE double-column conference template, with a 6 page limit, allowing 1 additional page with an additional charge. The best paper voted by the TPC will receive A BEST PAPER award. Selected papers will be featured in a Special Issue of the “Internet Technology Letters” (John Wiley & Sons)

Check for more submission information at the workshop’s website: [http://mobislice.com](http://mobislice.com)

**Important Dates**

- Paper submission: July 26, 2019
- Notification of Acceptance: August 30, 2019
- Camera-ready Submission: September 20, 2019

**Workshop Chairs**

- Daniel Corujo (University of Aveiro and Instituto de Telecomunicações, Portugal)
- Augusto Neto (Federal University of Rio Grande do Norte, Brazil)
- Seil Jeon (Huawei Technologies, Sweden)

**TPC Chairs**

- Prof. Dr. Rui L. Aguiar, Universidade de Aveiro e Instituto de Telecomunicações, Portugal
- Prof. Dr. Christian Rothenberg, (Universidade de Campinas, Brazil)